ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES	al Composition De ght 2005. IPC, Bannock nal and Pan-American of	claration burn, Illinois. A opyright conver	ll rights reserved u utions.	nder both	This docume level parts, tl	ent is a declaration e	on of the substancompasses all	nces within the mar ower level materia	nufacturer liste ls for which the	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
759_91 1	IPC Web Site for Information on IPC-1752 Standard Form			Form Type * Distribute					Materials and	tials and Mfg Information			
upplier Information													
ompany name*	Company uni	Company unique ID			Unique ID Authority				Response Date*				
nsemi									2025-05-14				
ontact Name	Title - Contac	Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA			Prod	Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repres	Title - Representative			Phone - Representative*			Emai	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA			Prod	Product-Env-Stewards@onsemi.com				
Requester Item Numb			umber Mfr Item Name			Effective Date	Version	Manufacturing	Site	Weight*	UOM	Unit Type	
	NXH16 S1G	NXH160T120L2Q2F2 Mass PIM 1200 S1G (Insourcing)		, 160A Split TNPC		2025-05-14		CNG		175618.11	mg	Each	
Ianufacturing Proccess	Information												
Terminal Plating / Grie	Terminal Plating / Grid Array Material Terminal I		e Alloy J-STD-020 MSL R		Rating	Peak Process Body Temperature Max Time at		at Peak Tempe	ak Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0	0 C 30		sec	seconds 3			
omments													
or more information regarding	g material composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted					
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Case	10330.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3	2	3615.5	mg
		8	Supplier	PBT	26062-94-2		6714.4995	mg
Case Lid	6690.0	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		2341.5	mg
			Supplier	РВТ	26062-94-2		4348.5	mg
DBC	17490.0	mg	Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		6996	mg
			Supplier	Copper (Cu)	7440-50-8		10494	mg
Die	219.105	mg	Supplier	Silicon (Si)	7440-21-3		219.105	mg
Glue	410.0	mg	Supplier	2,3-epoxypropyl-trimethoxysilan	2530-83-8		41	mg
			Supplier	Miscellaneous	Trade Secret		41	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		328	mg
Heat Sink	123450.0	mg	В	Nickel (Ni)	7440-02-0		1913.475	mg
			Supplier	Copper (Cu)	7440-50-8		121536.5234	mg
NTC	10.0	mg	Supplier	Silver (Ag)	7440-22-4		0.0979	mg
			Supplier	Tin (Sn)	7440-31-5		0.02	mg
			Supplier	Nickel Oxide (NiO)	1313-99-1		3.9169	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0999	mg
			В	Nickel (Ni)	7440-02-0		0.01	mg
			Supplier	Cobalt Oxide (Co3O4)	1308-06-1		0.3997	mg
			Supplier	Manganese Tetraoxide (Mn3O4)	1317-35-7		5.4556	mg
Silicone Gel	8400.0	mg	Supplier	Silica, [(ethenyldimethylsilyl)oxy]- and [(trimethylsilyl)oxy]- modified	68988-89-6		2520	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5880	mg
Solder Paste	5040.0	mg	Supplier	Silver (Ag)	7440-22-4		327.6	mg
			Supplier	Tin (Sn)	7440-31-5		4712.3999	mg
			Supplier	Copper (Cu)	7440-50-8		-151.2004	mg
Terminal	3540.0	mg	Supplier	Silicon (Si)	7440-21-3		9.558	mg
			В	Nickel (Ni)	7440-02-0		47.79	mg
			Supplier	Copper (Cu)	7440-50-8		3481.7671	mg
			Supplier	Phosphorus (P)	7723-14-0		0.885	mg
Wire Bond - Al	39.0	mg	Supplier	Aluminum (Al)	7429-90-5		39	mg